

JPCA Show

53rd International Electronic Circuits Exhibition

JIEP Microelectronics Show

38th ADVANCED ELECTRONICS PACKAGING EXHIBITION

JISSO PROTEC

25th Jisso Process Technology Exhibition

METaverse DEVICE EXPO
メタバースデバイス展
METAVERSE DEVICE EXPO

Connecting Machine to Machine
WIRE Japan Show
Electrical / Optical Transmission Technology

Electronics Component & Unit Show
JEP Japan Federation of Electronic Parts Distributors and Dealers
TEA Tokyo Electronics Appliances Wholesalers Association

E-Textile/Wearable

Smart Sensing

無人化ソリューション展

Automated Solution Exhibition

Edge Computing



The Exhibition Guide

The Total Solution Exhibition for Electronic Equipment 2024

2024. 6. 12_{Wed.} → 14_{Fri.}

Tokyo Big Sight East Exhibition Halls

Application to Exhibit from: 10:00 am (JST), November 1, 2023



Official Website

Organizers: Japan Electronics Packaging and Circuits Association, Japan Institute of Electronics Packaging, Japan Robot Association

Co-organizers: Electronic Device Industry News (Sangyo Times, Inc.)
Electric Wire & Cable News (KOGYO TSUSHIN CO., LTD)
JTB Communication Design, Inc.
Japan Federation Of Electronic Parts Distributors and Dealers
Tokyo Electronics Appliances Wholesalers Association
SENKEN SHIMBUN CO.,LTD.

Sponsor (tentative): Ministry of Economy, Trade and Industry

Overseas Cooperation:

World Electronic Circuits Council (WECC) Member Associates:
China Printed Circuit Association (CPCA), European Institute of Printed Circuits (EIPC),
Hong Kong Printed Circuit Association (HKPCA), IPC-Association Connecting Electronics Industries (IPC),
Indian Printed Circuit Association (IPCA), Electronic Industries Association of India (ELCINA),
Korea Printed Circuit Association (KPCA), Thailand Printed Circuit Association (THPCA),
Taiwan Printed Circuit Association (TPCA)

Association of Electronic Industries in Singapore (AEIS)
Korea Packaging Integration Association (KPIA)

As of Oct. 20, 2023

Come & Look WHAT we can OFFER for ELECTRONICS!!

500 exhibitors (tentative) wait you with cutting edge PCB, Assembly, Equipment, Process Materials and Components.

Exhibition Outline




Exhibition Period	Wednesday, June 12 to Friday, June 14, 2024, 10:00 a.m. - 5:00 p.m.		
Venue	Tokyo Big Sight East Exhibition Halls	Managed by	Japan Electronics Packaging and Circuits Association (JPCA)
Admission	1,000 Yen (including tax) * Free Admission for those who have pre-registered online.	Secretariat Office	JTB Communication Design, Inc.

Attractive Seminar Programs/Events

PCB, Assembly, PCB Related Equipment, Materials/Processes, High-speed Transmission Technology for Autonomous Driving, High-current Technology for EVs, Advanced Packaging Technology, Materials and Process Technology for Power Semiconductors/Glass Substrates, Low-emission Technology for Climate Change, E-Textile/Wearable Technology, Sensor & Sensing Technology, Automated Technology/Solutions, Edge Computing, On-Device technology, etc.

Exhibitions held inside the exhibition/relevant exhibits

Electronic circuits technology	High-density packaging technologies	Electronic Component Packaging Technologies
 <p>JPCA Show 53rd International Electronic Circuits Exhibition</p> <ul style="list-style-type: none"> ● PWB Tech Products and Technologies related to electronic circuit boards (Design & Simulation, Reliability & Inspection, Circuit Board Materials, Functional & Process Materials, Manufacturing equipment, Related Systems), etc. ● Module JAPAN Module board / Module Board mounting / Embedded Component Board, General technology for built-in parts (Design & Simulation, Reliability & Inspection, Circuit Board Materials, Functional & Process Materials, Manufacturing equipment, Related Systems), etc. ● Flexible Printed Circuits Products Area General technology for Flexible Printed Circuits (Design & Simulation, Reliability & Inspection, Circuit Board Materials, Functional & Process Materials, Manufacturing equipment, Related Systems) ● EMS Japan Services and technologies related to EMS, ODM and contract manufacturing of semiconductors (Design & Simulation, Reliability & Inspection, Circuit Board Materials, Functional & Process Materials, Manufacturing equipment, Related Systems) <p>Organizer: Japan Electronics Packaging and Circuits Association</p>	 <p>JIEP Microelectronics Show 38th ADVANCED ELECTRONICS PACKAGING EXHIBITION</p> <p>General technology for implementation and electric technology (Materials / Circuit and Mounting design / High speed high frequency / Electromagnetic properties / Electronic parts / mounting / Optical circuit mounting / Environmental affinity implementation / Semiconductor Package / Micro mechatronics mounting technology / Related Manufacturing equipment)</p> <p>Organizer: Japan Institute of Electronics Packaging</p>	 <p>JISSO PROTEC 25th Jisso Process Technology Exhibition</p> <ul style="list-style-type: none"> ■ Electronic Component Placement Machines and related Equipment and Systems: electronic component placement machines (Mounter), electronic component insertion machines (Inserter), screen printers, soldering equipment (reflow oven), and dispensers ■ Packaging related Equipment and Systems: transfer systems, AGV, automatic warehouse, taping machines and materials, bulk feeders and other feeders, and automatic assembly machines, laser marking machine, cleaning equipment - cleaner ■ Semiconductor Packaging Machines and Systems: bonding equipment, flip chip packaging systems, COB systems ■ Industrial Robotics: handling robots, assembly robots, transport robots ■ Inspection/Test Equipment: automated optical inspection equipment, inspection/measuring equipment associated with semiconductor manufacturing ■ Packaging Design Systems: design tools, production optimizing software, and packaging programming equipment ■ Packaging Device Packaging Materials ■ Packaging Joining Systems - Solder/joining materials ■ High Frequency Compatible Devices, Components, and Materials ■ Environment related Devices and Materials <p>Organizer: Japan Robot Association</p>

METaverse DEVICE EXPO	Electrical/optical transmission technology	Semiconductors and Electronic parts	Highly functional textile
 <p>METaverse DEVICE EXPO</p> <p>Products and technologies related to the metaverse (Semiconductor (Processor, Memory, Sensor), AR • VR • MR/goggle / Display (micro LED • OLED) / Camera/ Headset/Controller/Cooling device etc)</p> <p>Co-organizers: Japan Electronics Packaging and Circuits Association, Electronic Device Industry News (Sangyo Times, Inc.)</p>	 <p>Connecting Machine to Machine WIRE Japan Show</p> <p>Electrical / Optical Transmission Technology</p> <p>General transmission technology for using wire and cable (Industrial equipment / Electrical wire, cable and connector / Electric wire processing machine / Wiring material / Wire Harness / Measuring instrument for electric wire and cable / Various devices + D116 / Inspection technology / M2M transmission / Optical transmission)</p> <p>Co-organizers: Japan Electronics Packaging and Circuits Association, Cable News (KOGYO TSUSHIN CO., LTD)</p>	 <p>Electronics Component & Unit Show</p> <p>JEP Japan Federation Of Electronic Parts Distributors And Dealers TEA Tokyo Electronics Appliances Wholesalers Association</p> <p>General technology for solutions by Semiconductors and Electronic parts (Semiconductors / Electronic Devices / Sensors / Mechanical Devices / FA control equipments / Measuring instruments / Power Sources / IoT and M2M Solution / Manufacturing solution system)</p> <p>Co-organizers: Japan Federation Of Electronic Parts Distributors And Dealers, Tokyo Electronics Appliances Wholesalers Association</p>	 <p>E-Textile/Wearable</p> <p>A mix e-textile of electronic technology, fiber and clothing (General technology for smart textile, stretchable and wearable (Textile material / Conductive material / material / Knitting / weaving technology / Print marking technology / Films)</p> <p>Co-organizers: Japan Electronics Packaging and Circuits Association, SENKEN SHIMBUN CO., LTD.</p>

Sensor technology	Automated technology/Automated Solution	Edge solution technology
 <p>Smart Sensing</p> <p>General technology for Sensor and Sensing System (Sensors, Sensor Nodes, Semiconductors, Parts and Devices, Electronics, Telecommunications Devices, Network Systems, Software, Data Platform, Power Sources, Other Related Devices, Technologies and Services)</p> <p>Co-organizers: Japan Electronics Packaging and Circuits Association, JTB Communication Design, Inc.</p>	 <p>Automated Solution Exhibition</p> <p>Automated technology / Automated Solution, Monitoring system / Remote control system / ADAS/Deep learning / Noncontact system / Touchless system / AR/Anomaly detection system / facial recognition system / AI etc.</p> <p>Co-organizers: Japan Electronics Packaging and Circuits Association, JTB Communication Design, Inc.</p>	 <p>Edge Computing</p> <p>Advantageous general edge solutions for areas such as low delay, high safety and low communication volume [Edge Application Areas] Automatic operation system / Factory Automation / Telemedicine / AR/VR / Smart city / Agritech / FinTech / Unmanned store, etc.</p> <p>Co-organizers: Japan Electronics Packaging and Circuits Association, JTB Communication Design, Inc.</p>

NEW Application zones If you wish to exhibit in the Application Zone, please select the zone when applying to exhibit.

Automated Driving High-speed Transmission Technology Zone for Automated Driving	EV (electric vehicle) High Current Technology Zone for EV	Power Semiconductor/Glass Substrates Materials and Process Technology Zone for Power Semiconductors / Glass Substrates
Advanced Packaging Advanced Semiconductor Packaging Technologies Zone for Chiplets, etc.	Climate Change Solutions Low Emission Technology Zone Contributing to Climate Change Mitigation	

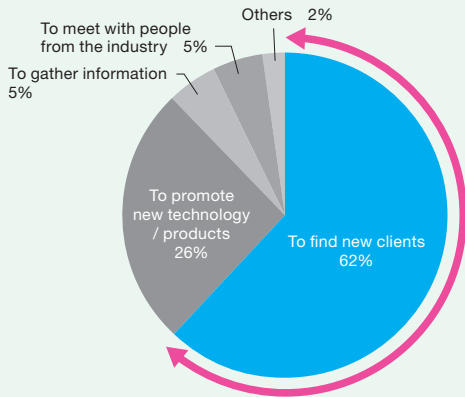
Venue Tokyo Big Sight East Exhibition Halls

Exhibit scale 517 companies / 1,273 booths

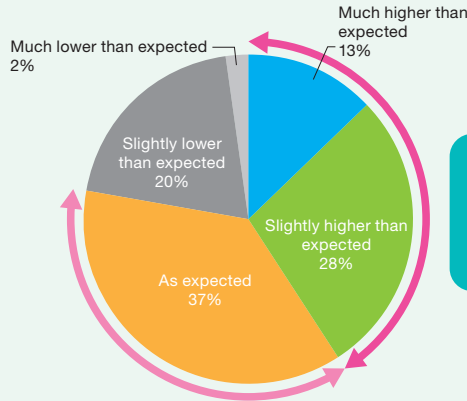
Number of visitors 48,018 people

Exhibitors Questionnaire

1. Reasons for exhibiting

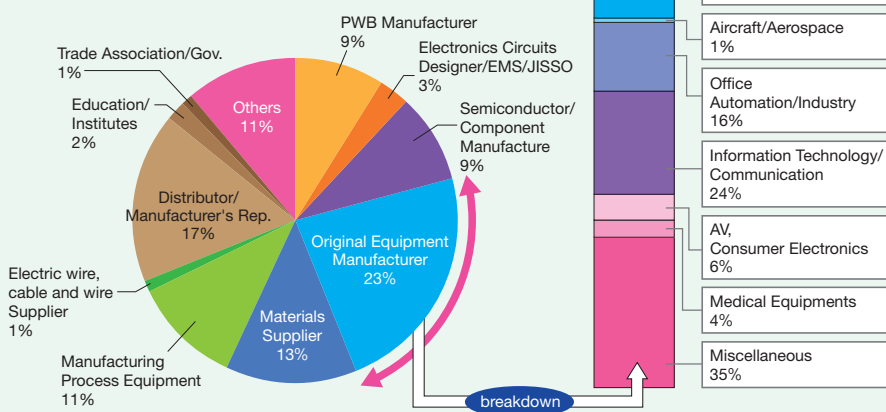


2. Effects of exhibiting



Exhibited for the purpose of developing new customers, 41% of exhibitors exceeded expectations, 78% of exhibitors exceeded expectations.

Industry Classification of Visitors



Not limited to traditional electronics and electrical equipment manufacturing visitors, networking with visitors from new application fields is expected. networking with visitors from new application fields is expected.

attention Providing new networking opportunities!

Exhibitor Networking Meetings will be held to promote networking among exhibitors!

"Student Welcome Booth" and "Exchange Plaza for Students" will be set up to welcome young generation that will be responsible for tomorrow's electronics!

Expected VISITORS

Visitors from a wide variety of industries and Sectors!

Semiconductors, Telecommunications, Mobility (Automobiles, Motorcycles, Bicycles), Shipping, Trains, Aircraft, Agriculture, Transportation Infrastructure, Logistics, Gaming and Toys, Metaverse, AI, AR/VR, Forestry, Fisheries, Food, Education, Medical, Apparel/Sports Equipment, Finance, Local Government, Beauty, Smart Home Appliances, Defense Equipment, e-Sports, AV, Drones, Wearable Devices, Sensors, Disaster Prevention, Robotics, Biometrics, Energy, Dx/Gx/Cx/Sx, Tourism Dx, Signage, SmartX, etc.

- AGC / AmkorTechnology / CKD / DIC / HUAWEI / JA-group / JFE Group / East Japan Railway Company Group / JSR / JTB / JVCKENWOOD / KDDI Group / LG Group / LIXIL / NEC Group / NHK Technologies / NTN / NTT Group / Rapidus / SK Group / SMBC Group / SUBARU / SUMCO / TDK / THK / TOTO / TSMC Group / YKK / AISIN Group / ASAHI SOFT DRINKS / AEON Group / Intel / OKAMURA / OMRON Group / Olympus / CASIO COMPUTER / National Research Council of Canada / KANSAI ELECTRIC POWER Group / Canon / KINDEN / KUBOTA / CITIZEN WATCH Group / Sharp / Shachihata / Seiko Watch / ZEON / SECOM / Sony Group / SoftBank / Tiger / DUSKIN / Terumo / Television Saitama / TV TOKYO / Deloitte Tohmtsu Consulting / DENSO Group / TOENEC / TOYOTA MOTOR / TOYOTA AUTO BODY / NIKON / NIPRO Group / NORITAKE / PARK24 / HASEKO Group / Panasonic Group / HIROSE ELECTRIC / Foster Electric / BROTHER INDUSTRIES / Bridgestone Group / Hosiden / MISAWA HOMES / Mizuho Financial Group / Yamaha / Ricoh / Resona Group / Rinnai / Resonac / Lenovo Japan / ROHM Group / Aisan Industry / Aichi Steel / Asahi Kasei / Yaskawa Manufacturing / ITOCHU / Japan Aerospace Exploration Agency / Yokogawa Electric / The Bank of Yokohama / YOKOHAMA National University / KAGA ELECTRONICS / Marubeni / Iwatani / KYOCERA / KYUSHU UNIVERSITY / Kyushu Electric Power / Keio University / KANEMATSU / Furukawa Electric / TODA / KURODA ELECTRIC / Mitsui Chemicals / MUFG Bank / MITSUBISHI MOTORS / Mitsubishi / Mitsubishi Research Institute / Mitsubishi Electric / Sanwa Shutter / National Institute of Advanced Industrial Science and Technology / Shiseido / Kagoshima Prefecture / SUMITOMO / Sumitomo Wiring Systems / Idemitsu Kosan / The Shoko Chukin Bank / KOITO MANUFACTURING / Komori Corporation / MORINAGA MILK INDUSTRY / SHIMIZU / Kawasaki Heavy Industries / Kurabo Industries / Waseda University / SOHGO SECURITY SERVICES / Murata Manufacturing / TAIYO YUDEN / Osaka Research Institute of Industrial Science and Technology / OSAKA UNIVERSITY / Dai Nippon Printing / OBAYASHI / DAIWA HOUSE INDUSTRY / TEIJIN / SHIMADZ / Toray Industries / TOKAI RIKI / Tokyo Electron / TOKYO GAS / Tokyo Fire Department / The University of Tokyo / Tokyo Metro / TOSHIBA GROUP / TOHOKU UNIVERSITY / TOYOBO / Nanya Group / NICHIA / Nissan Motor / Nitto Boseki / IBM / Samsung C&T Japan / Texas Instruments Japan / Honeywell Japan / Nikkei / NIHON TOYO / Japan Radio / Hitachi Zosen / National Agriculture and Food Research Organization / Fuji Chimera Research Institute / FUJI SOFT / FUJIFILM Group / Fujitsu Group / Toyoda Gosei / TOYOTA INDUSTRIES / Honda Motor / MEIDENSHA / Nomura Research Institute / Nomura Securities / Yazaki / Yano Research Institute (in no particular order)

Overseas Visitors: from 27 countries/regions

Exhibition Fee

Category	1 booth/9m ² *Tax included
Non-Members	Yen 496,100
Members ^{*1}	Yen 423,500

*1 Members of the following associations

WECC Member Associations (OPCA, EIPC, ELCINA, HKPCA, IPC, IPCA, KPCA, THPCA, TPCA)
AEIS, KPIA

* Size of a booth is 9m² (3m × 3m).

* Fee is for raw space only, Booth construction, cleaning, electricity, water supply, etc. are not included in the exhibition fee.

How to apply (From November 1, 2023 (Wed.) 10:00a.m (JST))

Please apply online on our website. (www.jpccashow.com)

If you use the Application Form, please apply by e-mail or FAX.

Please select the exhibition based on your products, technologies or services and carefully read the "Exhibition Regulations" on the back of the Application Form.

For the exhibition which has the exclusive application form, the relevant exhibition regulations shall be applied.

An invoice will be issued upon receipt of your application.

Please download the invoice from each exhibitor's website.

Application Deadline

Thursday, February 29, 2024

If all spaces are reserved before the deadline, the application will no longer be accepted.

Cancellation charges

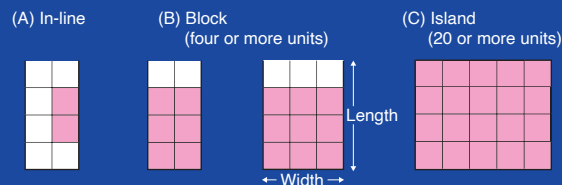
If an exhibit is cancelled to suit the exhibitor's circumstances, cancellation charges (full or partial fees) shall apply as below.

Date of receipt of written notice of cancellation	Cancellation charges
Until Thursday, February 29, 2024	30% of booth fees
Friday, March 1 - Sunday, March 31, 2024	50% of booth fees
Monday, April 1 - Tuesday, April 30, 2024	70% of booth fees
From Wednesday, May 1, 2024 onward	100% of booth fees

Schedule prior to the Exhibition (Tentative)

2023 November	2024 February	March	April	May	June
▲ November 1 (Wed.) 10:00 – Start of Exhibition Application	▲ February 29 (Thur.) Exhibitor application deadline	▲ Mid-March Exhibitor Manual available	▲ Mid-April Sending Invitations Visitor Registration begins		▲ June 10 (Mon.) - 11 (Tue.) Installation period
		▲ Late March Booth Location Selection Meeting			▲ June 12 (Wed.) - June 14 (Fri.) Exhibition open
		← Mid-March onwards Submission of necessary forms →			
					* Immediate removal on the last day

Booth type



* In some cases, it may not be possible to prepare the requested booth type.

Assignment of Booth Locations

Booths will be assigned at the Booth Location Selection Meeting (Scheduled to be held in late March 2024).

As a rule, exhibitors will be able to choose their booth locations on a first-come-first-served basis.

* For details, please refer to the Exhibitor Rules and Regulations.

Exhibitor Support Program Option

Promotion services will provide an opportunity to increase your presence at the exhibition.

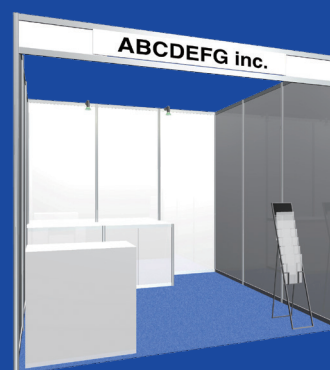
Package booth Option

● 1 booth / basic plan

Price: 118,800 Yen (Tax included)

This plan includes the minimum necessary booth fixtures and fittings, power supply and carpet.

For more details, please refer to the document to be distributed around mid-March 2024.



Managed by

Japan Electronics Packaging and Circuits Association (JPCA)

Kairo Kaikan 2F, 3-12-2, Nishiogikita, Sugunami-ku, Tokyo 167-0042

TEL: +81-3-5310-2020 FAX: +81-3-5310-2021 E-mail: show@jpcca.org

Operated by

JTB Communication Design, Inc.

Celestine Shiba Mitsui Building, 3-23-1, Shiba, Minato-ku, Tokyo, Japan 105-8335

TEL: 81-3-5657-0767 FAX: 81-3-5657-0645 E-mail: jpcashow@jtbcom.co.jp



Official Website

<h1 style="margin:0;">Application Form</h1> <p style="margin:0;">The Total Solution Exhibition for Electronic Equipment 2024 *June 12-14, 2024 Tokyo Big Sight</p>	<h2 style="margin:0;">Deadline</h2> <h1 style="margin:0;">February 29, 2024</h1>
<p>Sent to Secretariat Office (I/C JTB Communication Design, Inc.) Celestine Shiba Mitsui Building, 3-23-1, Shiba, Minato-ku, Tokyo, Japan 105-8335 TEL. +81-3-5657-0767 FAX. +81-3-5657-0645</p> <p style="text-align: right; font-weight: bold; font-size: 1.2em;">Mail: jpcashow@jtbc.com.co.jp</p>	

To: Japan Electronics Packaging and Circuits Association

We apply for the exhibition in consent with the "Exhibition Regulations" and "handling of personal information" (the reverse side of this form). (required)

[GDPR Notice] *https://www.jpcashow.com/show2024/common/pdf/JPCA2024_GDPR.pdf Date: DD _____ MM _____ YY _____

Name of Company or Organization			
Applicant	Department	Title	Name
Contact	Address		
	Zip code	Name	
	TEL	FAX	
	Email		
<input type="checkbox"/> Co-Exhibitor (Sharing the booth)			
Name of Company or Organization			

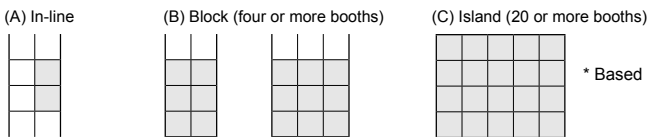
☉ If you have any representative in Japan for the 2024 show, please fill-in with their contact information.

Company Name	Contact Person		
Address		Email	
Department	Title	TEL	

Exhibition fees / Booth selection

*See the Exhibition Guide for details.

Non-member		Yen 496,100 ×	booths	= Yen
Member	WECC Member Associations (<input type="checkbox"/> CPCA <input type="checkbox"/> EIPC <input type="checkbox"/> ELCINA <input type="checkbox"/> HKPCA <input type="checkbox"/> IPC <input type="checkbox"/> IPCA <input type="checkbox"/> KPCA <input type="checkbox"/> THPCA <input type="checkbox"/> TPCA) <input type="checkbox"/> AEIS <input type="checkbox"/> KPIA	Yen 423,500 ×	booths	= Yen
	Booth type (see below).	<input type="checkbox"/> (A) In-line <input type="checkbox"/> (B) Block (four or more booths) <input type="checkbox"/> (C) Island (20 or more booths)		



Total
Yen _____ (*Tax included)

The Exhibition you would like to exhibit at and the product to be exhibited (*select only one check box)

(*If you apply for more than one location, please apply for each location separately.)

JPCA Show

- PWB Tech
- Module Japan
- Flexible Printed Circuits Products Area
- EMS Japan

- Microelectronics Show**
- JISSO PROTEC**
- METaverse Device Expo**
- WIRE Japan Show**

- [Zone] High-speed Transmission Technology Zone for Automated Driving
- [Zone] High Current Technology Zone for EV
- [Zone] Materials and Process Technology Zone for Power Semiconductors/Glass Substrates
- [Zone] Advanced Packaging Technology Zone
- [Zone] Climate Change Solutions : Low Emission Technology Zone

Exhibited product/Technical field (* select only one check box)

- 1. Finished Products
- 2. Design Technologies
- 3. Reliability and Inspection Technologies
- 4. Main Materials
- 5. Processing Technologies, Materials, and Equipment
- 6. Manufacturing Equipment
- 7. Environmental Systems
- 8. Distribution Systems
- 9. Other

Products to be exhibited, Technical fields (free)

Remarks / Special Request

Secretariat use only		
Receipt No.	Confirmation by secretariat	Invoice No.

In order to apply for the following exhibitions, please use the designated application form.

- | | |
|---|--|
| <p>Electronics Component & Unit Show</p> <p>E-Textile/Wearable</p> <p>Automated Solution Exhibition</p> | <p>Smart Sensing</p> <p>Edge Computing</p> |
|---|--|

1. Formation of Contract

Upon receipt of the application form by the Organizer through the online exhibition application system, the contract for this exhibition shall be officially confirmed. JPCA reserves the right to refuse to accept the application. In such cases, JPCA shall not state the reasons for the refusal.

(1) Handling of joint application by two or more companies jointly participate in the exhibition In case two or more companies that have applied for exhibition individually wish for adjacent or nearby booth positions, they shall notify the organizer of the tie-up exhibition at the time of application.

In case two or more companies apply to exhibit together in the same booth, one company should apply as a representative and notify the organizer of the names of the companies that will be co-exhibiting.

(2) Refusal of Application for Exhibition

Applications will not be accepted from those that are filing for bankruptcy, composition, corporate reorganization, civil rehabilitation or corporate reorganization law procedures, those subject to suspension of current transactions from financial institutions, those engaged in or involved in anti-social activities, or those subject to administrative punishment such as an order to suspend business operations.

In addition, the same shall apply in the event that the organizer deems that the applicant is equivalent to the above.

Even after the confirmation of the contract, if the exhibitor should fall into any of the above, the contract shall be cancelled and the application shall be refused.

In this case, any exhibition fees that have already been paid will be fully refunded.

The Organizer may conduct investigations and reviews as deemed necessary in connection with the above.

(3) Application by electronic media, facsimile, etc.

In the event an application for exhibition cannot be made through the online exhibition application system due to unavoidable circumstances, an application via electronic media or fax will be accepted. In this case, the Secretariat will input the necessary information into the system on behalf of the applicant.

2. Basic Condition for Accepting Exhibit Application

The exhibitors shall agree to the exhibition purposes of JPCA Show, Microelectronics Show, JISSO PROTEC, METAVERSE Device EXPO, WIRE Japan Show, Electronics Component & Unit Show and E-Textile/Wearable are not allowed, in principle, to exhibit products and technologies which are not clearly shown in major target products and technologies for each exhibition described in the exhibition guide.

3. How to Pay Exhibition Fees

The exhibitors shall pay exhibition fees and any optional fees incidental thereto based on the invoice issued by Secretariat Office by the deadline noted on the invoice. The payment from the exhibitors shall be made to the designated bank account described in the invoice in Japanese yen. We don't take promissory notes, checks, etc. The bank transfer fees shall be paid by the exhibitors.

4. Exhibition Booth Fees Include as Follows:

- Booth lease fees
- Partition walls (panels) [in case that there are adjoining booths]
- Other services mandated by the secretariat for exhibitors
- Other expenses concerning visitor services
- Safety administrative expenses, expenses of necessary personnel and guard

5. Installation and Removal of Exhibits

The exhibitors must carry in and out decorative articles and exhibits in the booths according to the schedule decided by JPCA.

If an exhibitor needs to carry in or out or move exhibits during the exhibition period, it shall work on these tasks after the approval of JPCA.

6. Use of Exhibition Area

All the advertising and business activities shall be limited in the exhibition booths.

Each exhibitor shall have a responsibility to reduce crowdedness because of advertising activities in passages near each booth. Anything such as decorative articles shall not exceed the scope of allocated space.

If JPCA finds any problem with the sound, method of control, materials, or other aspects of decorative articles or exhibits, it shall have the right to prohibit or remove all the acts which go against the purposes of the exhibition.

In the event of exercising the right of the above restriction or removal, JPCA shall not be held liable to reimburse the exhibitors in any way or bear the associated costs.

7. Management of Exhibits and Indemnity

JPCA shall take the greatest possible care to the management and maintenance of the exhibition site, however, it shall not be liable for any loss or damage of exhibits caused by any other reasons.

8. Warranty Clause

(1) The contents such as images, videos, logo marks, various information, etc. posted by the exhibitor in the exhibition space at the exhibition belong to the exhibitor. It will be assumed that the exhibitor has given the organizer permission to publish information on the official website and various printed materials, advertisements, e-mail newsletters, media, etc. related to the exhibition of such content provided by exhibitors to the organizers for public relations activities of the exhibition.

(2) The exhibitors shall guarantee JPCA that the exhibits in the exhibition or the related printed materials and other medium concerning the exhibits will not infringe trademark rights, design rights, patent rights, utility model rights or any other intellectual property rights of any third party.

9. Obligation of Exhibitors

(1) In cases where there is a claim that the acts related to the exhibitors' participation in the exhibition infringe trademark rights, design rights, patent rights, utility model rights or any other intellectual property rights of any third party, the exhibitors shall have the obligation to JPCA to promptly settle such dispute with the third party at their own responsibility and not to hinder the normal and smooth progress of the exhibition

(2) In cases where a claim regarding the infringement of intellectual property rights occurs against an exhibitor who is a member of the group concerned from the third party, a responsible person for the group exhibitions shall have the same obligation set forth in the preceding paragraph.

10. Determination of Booth Location

Booths will be assigned at the Booth Location Selection Meeting (scheduled for the Late March, 2024)

As a rule, exhibitors will be able to choose their booth locations on a first-come-first-served basis. Details will be made available in the rules and regulations to be made public from 10:00 a.m. January 17th.

11. Cancellations of Exhibition Booths and Reduction of Number of Booths

If an exhibit is cancelled or the number of exhibition booths is reduced to suit the exhibitor's circumstances, cancellation charges (full or partial fees) shall apply as below.

Date of receipt of written notice of cancellation (by post, fax, or email)	Cancellation charges
Until Thursday, February 29, 2024	30% of booth fees
Friday, March 1 - Sunday, March 31, 2024	50% of booth fees
Monday, April 1 - Tuesday, April 30, 2024	70% of booth fees
From Wednesday, May 1, 2024 onward	100% of booth fees

12. Prohibition of Subletting, Selling, Transferring, or Exchanging of Exhibition Space

The exhibitors shall not sublet, sell, transfer, or exchange exhibition space, either in whole or in part, to any third party, including other exhibitors.

13. Notices for Exhibitors of Foreign Products and Foreign Exhibitors

(1) Bond procedure for exhibits from foreign countries

JPCA shall not apply for bonded exhibition site status. When the exhibitors would like to treat exhibits from overseas as bonded products, the exhibitors shall complete the bond procedure.

(2) Obtaining a visa

When foreign exhibitors need to obtain visas, the exhibitors shall assume responsibility for preparing the necessary documents including Letter of Guarantee and Letter of Reason for Invitation and complete the procedure.

JPCA shall not issue Letter of Guarantee and Letter of Reason for Invitation to the exhibitors. JPCA shall not be held liable to compensate for losses and/or damages arising from the inability for the exhibitor to participate in the exhibition, in the event the exhibitor are not successful in acquiring a visa.

14. Compensation for Damages

(1) The exhibitors shall be responsible for all damages to the venue facilities, buildings, or injuries to their personnel owing to negligence on the part of themselves or their agents, or for other reasons.

(2) The exhibitors shall agree to be obliged to make compensation to JPCA for legal costs, liabilities (including an attorney's fee), necessary expenses, and compensation for damages, caused by an action arising out of or as a result of claims in the following cases:

(a) In cases where a lawsuit is filed against JPCA, based on a claim that the acts related to the exhibitors' participation in the exhibition infringe trademark rights, design rights, patent rights, utility model rights or any other intellectual property rights of any third party (including the cases where JPCA as well as the exhibitors are regarded as defendants), or

(b) In cases where JPCA is liable for compensation for damages in a judgement, a court, or an out-of-court settlement due to such a lawsuit in (a), (JPCA shall not be subject to the intension of the exhibitors in terms of a settlement)

(3) JPCA shall bear no responsibility for typographical errors and omissions in sales promotion materials such as announcement advertising and a guide book for the exhibition.

15. Cancellation, suspension, change of Exhibition

(1) The organizer may cancel, suspend, shorten the period of, or change the schedule or venue of the exhibition if the organizer deems it impossible or difficult to hold and continue the exhibition in the event that:

① the land or building used for the venue becomes unavailable, and the organizer deems the land or building inappropriate for use;

② the organizer deems it not appropriate to hold the exhibition following a request or order for, or a request for consideration of, self-restraint or cancellation of events by the government, administration or any public agency; or

③ it becomes impossible to hold the exhibition on the occurrence of any event of force majeure, or the organizer deems it not appropriate to hold the exhibition.

(2) The force majeure events described in the preceding paragraph shall mean acts of God, including typhoons, heavy rain, tempests, floods and earthquakes, epidemics, public health risk, delay or suspension of service of public transportation systems, war, civil war, terrorist attacks, strikes and other causes not attributable to the organizer.

(3) In no event shall the applicant claim compensation against the organizer for any damages caused to the exhibitor resulting from any decision made by the organizer. In addition, the organizer shall not be liable for any damages, increased expenses or other unfavorable circumstances caused to the exhibitor as a result of any such decision.

(4) If the organizer decides to cancel or suspend the exhibition prior to or after the start of the exhibition period, exhibition fee will be refunded after deducting a reasonable amount of expenses incurred up to that time.

(5) In the event the exhibition fee has already been paid in accordance with (4), fees will be refunded after deducting the expenses incurred up to that time from the paid amount. In the event of an unpaid payment, the invoice for the exhibition fee shall be disregarded and a new invoice shall be issued for the expenses incurred. Exhibitors shall transfer payment of the exhibition fees in Japanese yen to the bank account designated below by the date listed on the invoice.

(6) Regarding the Exhibition, notwithstanding the above, if the exhibition is cancelled due to the novel coronavirus (COVID-19), the exhibition fee will be fully refunded.

16. Compliance with Provisions

The exhibitors shall comply with the set of provisions stipulated by JPCA.

17. Changes and Additions of Regulations

If any question arises regarding any matter not stipulated in the regulations or any provision hereof, the exhibitors shall abide by the decisions of JPCA.

JPCA shall reserve the right to make revision and/or supplement to this regulations with the notification to the exhibitors in each fiscal year in advance.

18. Governing Law

The contract shall be governed by the laws of Japan.

19. Agreement Jurisdictional Court

It is agreed that the court of jurisdiction for all disputes arising with regards to the contract shall be the Tokyo District Court.

[For the handling of personal information]

Japan Electronics Packaging and Circuits Association shall handle customers' personal information and ensure to protect such information, based on "Act on the Protection of Personal Information" and JPCA's "Personal Information Protection Policy" (<http://jepca.jp/contactus/privacy/>). The customers shall provide personal information after acknowledging this in advance.

- Your personal information shall be used for communication regarding the exhibition.

- Collected personal information shall not be provided to third parties.

- JPCA entrusts the handling of personal data to JTB Communication Design, Inc.

with which JPCA has signed beforehand a non-disclosure agreement, in order to ensure

smooth operation of the exhibition.

- If an individual requests disclosure of, correction of, addition to or deletion of the personal information he or she has provided, notification of purpose of use, termination of use, erasure of the personal information, and cessation of supply of such personal data to a third party, JPCA shall promptly cope with such requests.

Please contact the personal information protection manager to which the JPCA is entrusted.

Hirohisa Hasegawa (Mr.)

General Manager, Tradeshow Business Unit, Co-Creation Department, JTB Communication Design, Inc.

Contact: +81-3-5657-0623

- Personal information provided to JPCA is done so at the discretion of the customers.

If you fail to provide necessary personal data, each service, etc. may not be provided to you in an appropriate manner.

- No methods that are difficult for you to be aware of shall not be used to acquire personal information.

If you have any questions, please contact the below.

Managed by:

Japan Electronics Packaging and Circuits Association

Kairo Kaikan 2F, 3-12-2, Nishiogikita, Suginami-ku, Tokyo 167-0042 Japan

Phone: +81-3-5310-2020 Fax: +81-3-5310-2021 E-mail: show@jepca.org

Secretariat Office (I/C JTB Communication Design, Inc.)

Celestine Shiba Mitsui Building, 3-23-1, Shiba, Minato-ku, Tokyo, Japan 105-8335

Tel: +81-3-5657-0767 Mail: jpcashow@jtbcom.co.jp